

The 2024 International Workshop on the High Energy Circular Electron
Positron Collider

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Type: **Talk**

**Manufacturing and assembly processes of TSV
(Through-Silicon Via) and sensor applications**

Friday, 25 October 2024 11:45 (15 minutes)

from NCAP

TSV 制造与组装工艺及传感器应用 (华进半导体)

Presenter: Mr REN, Zhengyu (NCAP)

Session Classification: International Industrial Connection